

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A ~~motherboard~~ device comprising:

a substrate;

a an interposer on said substrate;

a DC-to-DC converter secured on said interposer; and

contacts located between the interposer and substrate, wherein said contacts are located all around a die on the substrate.

Claim 2 (Currently Amended): The ~~motherboard~~ device of claim 1, wherein the substrate contains power sockets.

Claim 3 (Currently Amended): The ~~motherboard~~ device of claim 2, wherein the contact compresses into the power sockets to provide electrical connection.

Claim 4 (Currently Amended): The ~~motherboard~~ device of claim 1, wherein said contacts are located underneath the interposer.

Claim 5 (cancelled)

Claim 6 (Currently Amended): The ~~motherboard~~ device of claim 1, wherein the contacts are made of copper.